

Lonten N-channel 650V, 11A, 0.38Ω LonFET™ Power MOSFET

Description

LonFET™ Power MOSFET is fabricated using advanced super junction technology. The resulting device has extremely low on resistance, making it especially suitable for applications which require superior power density and outstanding efficiency.

Features

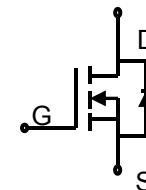
- ◆ Ultra low $R_{DS(on)}$
- ◆ Ultra low gate charge (typ. $Q_g = 22.8\text{nC}$)
- ◆ 100% UIS tested
- ◆ RoHS compliant

Applications

- ◆ Power factor correction (PFC).
- ◆ Switched mode power supplies (SMPS).
- ◆ Uninterruptible power supply (UPS).

Product Summary

$V_{DS} @ T_{j,max}$	700V
$R_{DS(on),max}$	0.38Ω
I_{DM}	30A
$Q_{g,typ}$	22.8nC


TO-220NF

N-Channel MOSFET


Absolute Maximum Ratings

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DSS}	650	V
Continuous drain current ($T_C = 25^\circ\text{C}$)	I_D	11	A
($T_C = 100^\circ\text{C}$)		7	A
Pulsed drain current ¹⁾	I_{DM}	30	A
Gate-Source voltage	V_{GSS}	± 30	V
Avalanche energy, single pulse ²⁾	E_{AS}	270	mJ
Power Dissipation ($T_C = 25^\circ\text{C}$)	P_D	33	W
- Derate above 25°C		0.26	$\text{W}/^\circ\text{C}$
Operating and Storage Temperature Range	T_J, T_{STG}	-55 to +150	$^\circ\text{C}$
Continuous diode forward current	I_S	11	A
Diode pulse current	$I_{S,pulse}$	30	A

Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	3.8	$^\circ\text{C}/\text{W}$
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	80	$^\circ\text{C}/\text{W}$
Soldering temperature, wavesoldering only allowed at leads. (1.6mm from case for 10s)	T_{sold}	260	$^\circ\text{C}$

Package Marking and Ordering Information

Device	Device Package	Marking	Units/Tube
LSDN65R380GT	TO-220NF	LSDN65R380GT	50

Electrical Characteristics

$T_c = 25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Static characteristics						
Drain-source breakdown voltage	BV_{DSS}	$V_{\text{GS}}=0 \text{ V}, I_{\text{D}}=0.25 \text{ mA}$	650	-	-	V
Gate threshold voltage	$V_{\text{GS(th)}}$	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=0.25 \text{ mA}$	2.5	3.5	4.5	V
Drain cut-off current	I_{DSS}	$V_{\text{DS}}=650 \text{ V}, V_{\text{GS}}=0 \text{ V}, T_j = 25^\circ\text{C}$	-	-	1	μA
Gate leakage current, Forward	I_{GSSF}	$V_{\text{GS}}=30 \text{ V}, V_{\text{DS}}=0 \text{ V}$	-	-	100	nA
Gate leakage current, Reverse	I_{GSSR}	$V_{\text{GS}}=-30 \text{ V}, V_{\text{DS}}=0 \text{ V}$	-	-	-100	nA
Drain-source on-state resistance	$R_{\text{DS(on)}}$	$V_{\text{GS}}=10 \text{ V}, I_{\text{D}}=5.5 \text{ A}$ $T_j = 25^\circ\text{C}$ $T_j = 150^\circ\text{C}$	-	0.34	0.38	Ω
Gate resistance	R_{G}	$f=1 \text{ MHz}, \text{open drain}$	-	5.55	-	Ω
Dynamic characteristics						
Input capacitance	C_{iss}	$V_{\text{DS}} = 100 \text{ V}, V_{\text{GS}} = 0 \text{ V},$ $f = 250 \text{ kHz}$	-	1068	-	pF
Output capacitance	C_{oss}		-	39	-	
Reverse transfer capacitance	C_{rss}		-	1.8	-	
Turn-on delay time	$t_{\text{d(on)}}$	$V_{\text{DD}} = 400 \text{ V}, I_{\text{D}} = 5.5 \text{ A}$ $R_{\text{G}} = 4.7 \Omega, V_{\text{GS}} = 10 \text{ V}$	-	15	-	ns
Rise time	t_r		-	27	-	
Turn-off delay time	$t_{\text{d(off)}}$		-	69	-	
Fall time	t_f		-	11	-	
Gate charge characteristics						
Gate to source charge	Q_{gs}	$V_{\text{DD}} = 520 \text{ V}, I_{\text{D}} = 5.5 \text{ A},$ $V_{\text{GS}} = 0 \text{ to } 10 \text{ V}$	-	6.2	-	nC
Gate to drain charge	Q_{gd}		-	8.5	-	
Gate charge total	Q_g		-	22.8	-	
	V_{plateau}		-	5.5	-	V
Reverse diode characteristics						
Diode forward voltage	V_{SD}	$V_{\text{GS}}=0 \text{ V}, I_{\text{F}}=5.5 \text{ A}$	-	1.0	-	V
Reverse recovery time	t_{rr}	$V_R = 400 \text{ V}, I_{\text{F}} = 11 \text{ A},$ $dI_{\text{F}}/dt = 100 \text{ A}/\mu\text{s}$	-	345	-	ns
Reverse recovery charge	Q_{rr}		-	3.8	-	μC
Peak reverse recovery current	I_{rrm}		-	22	-	A

Notes:

- Limited by maximum junction temperature, maximum duty cycle is 0.75.
- $I_{\text{AS}} = 3 \text{ A}, V_{\text{DD}} = 60 \text{ V}, \text{Starting } T_j = 25^\circ\text{C}.$

Electrical Characteristics Diagrams

Figure 1. On-Region Characteristics

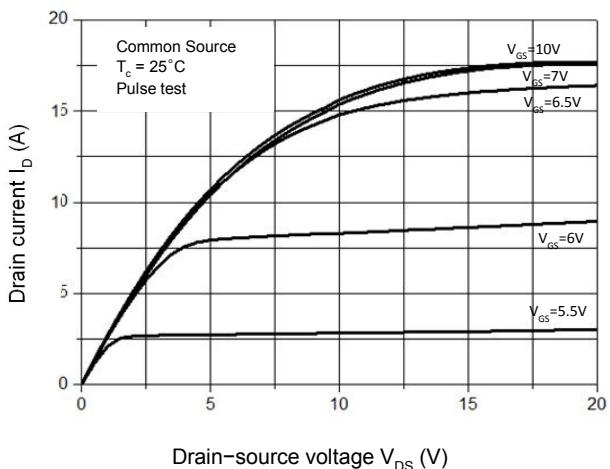


Figure 2. Transfer Characteristics

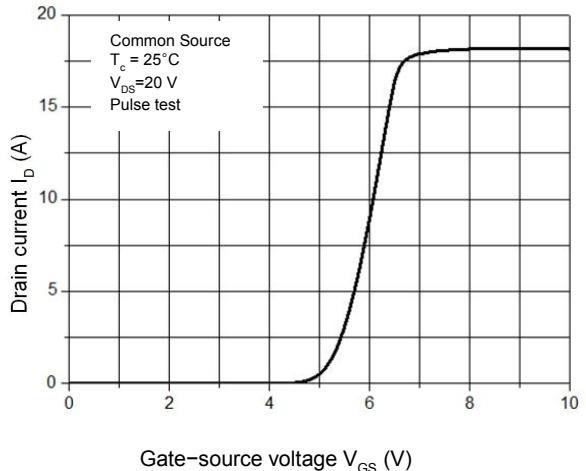


Figure 3. On-Resistance Variation vs. Drain Current

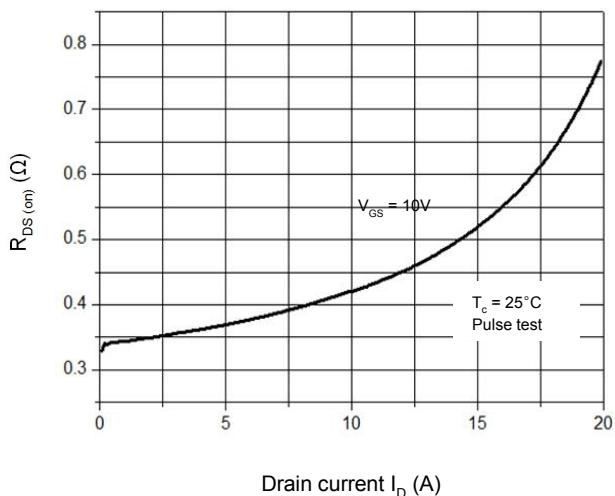


Figure 4. Threshold Voltage vs. Temperature

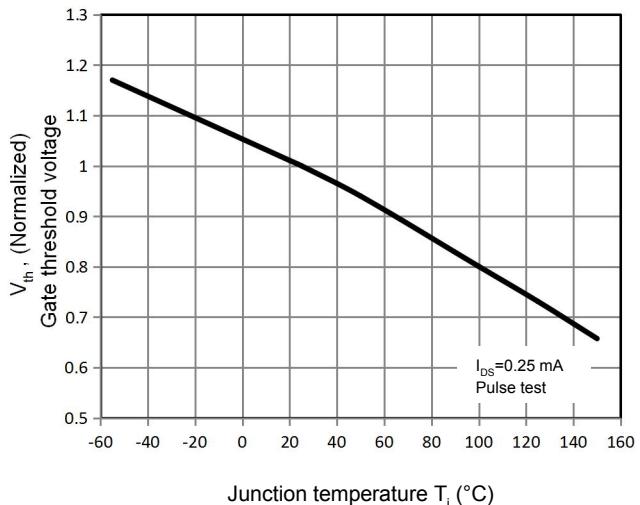


Figure 5. Breakdown Voltage vs. Temperature

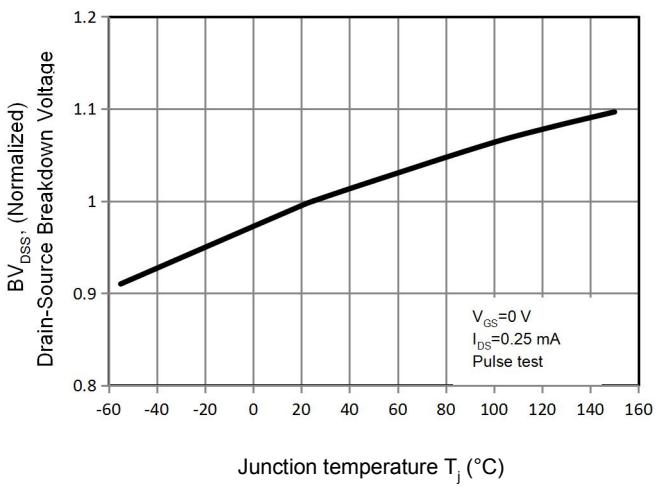


Figure 6. On-Resistance vs. Temperature

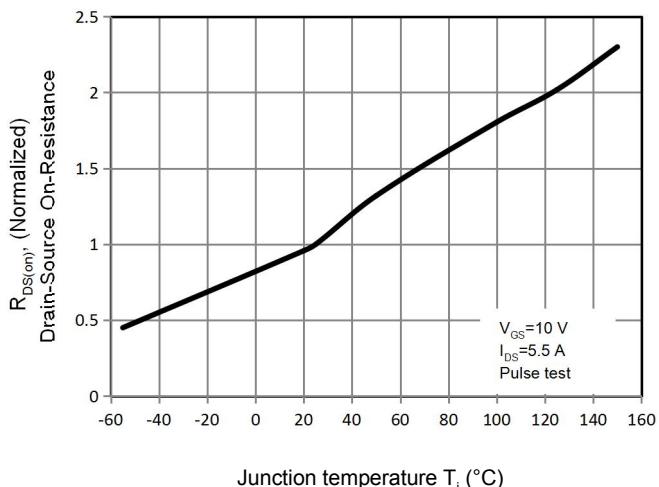


Figure 7. Capacitance Characteristics

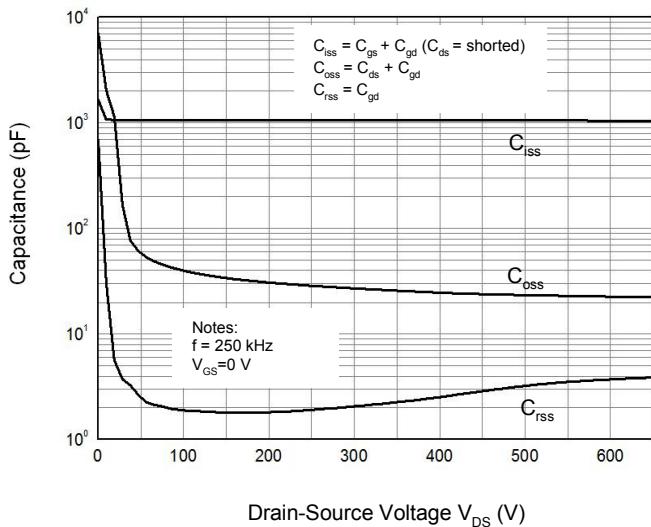


Figure 8. Gate Charge Characteristics

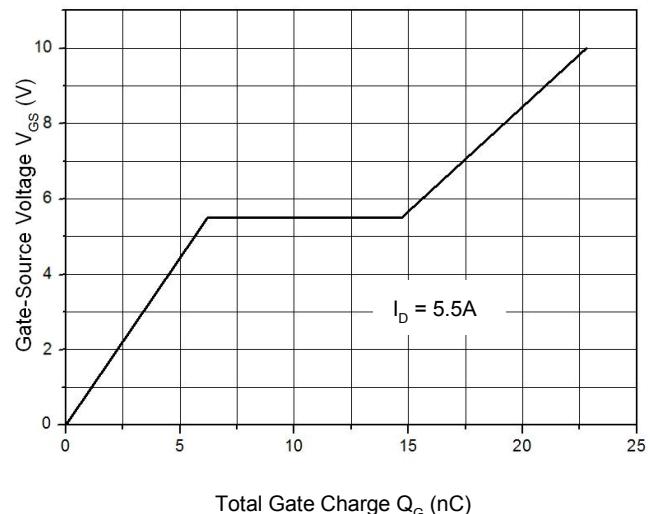


Figure 9. Power Dissipation vs. Temperature

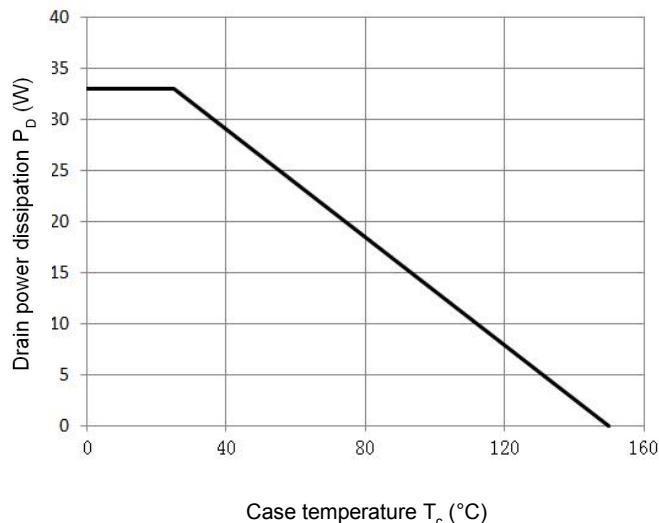


Figure 10. Drain Current Derating

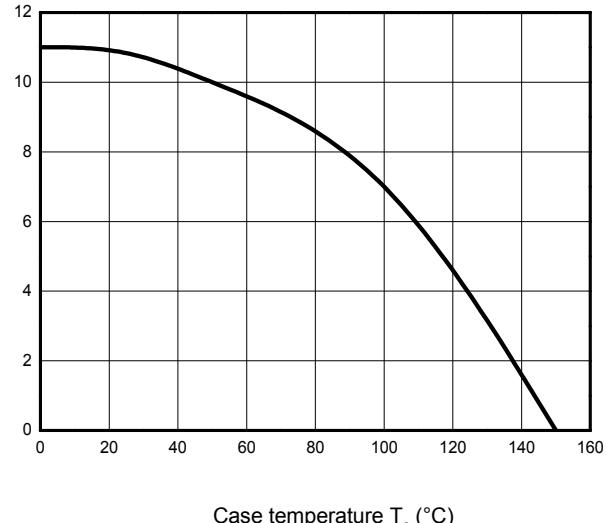


Figure 10: Safe Operating Area

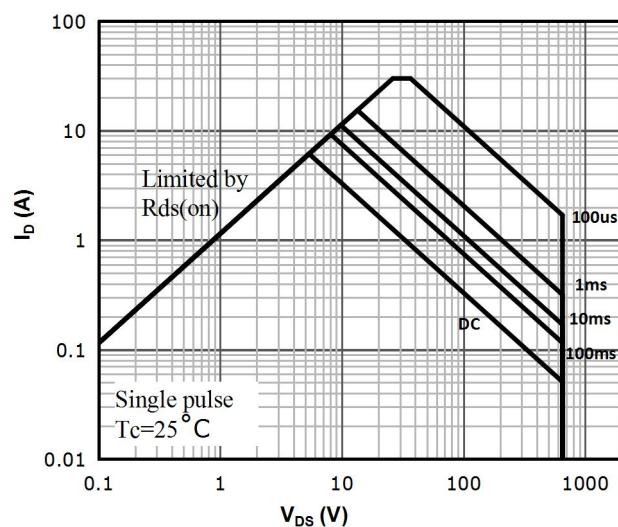
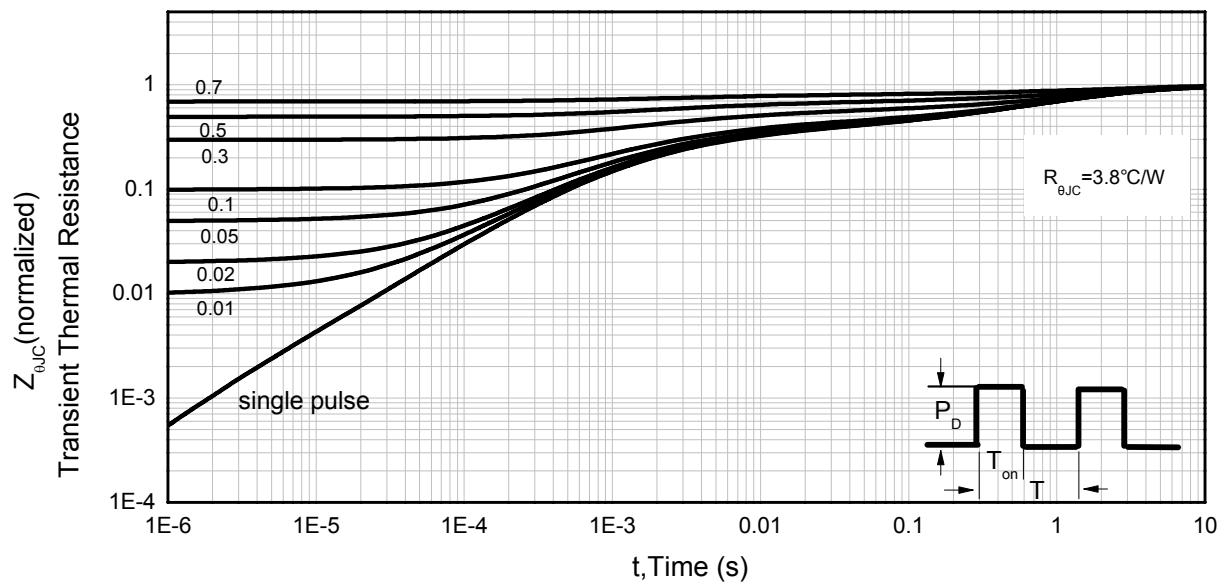
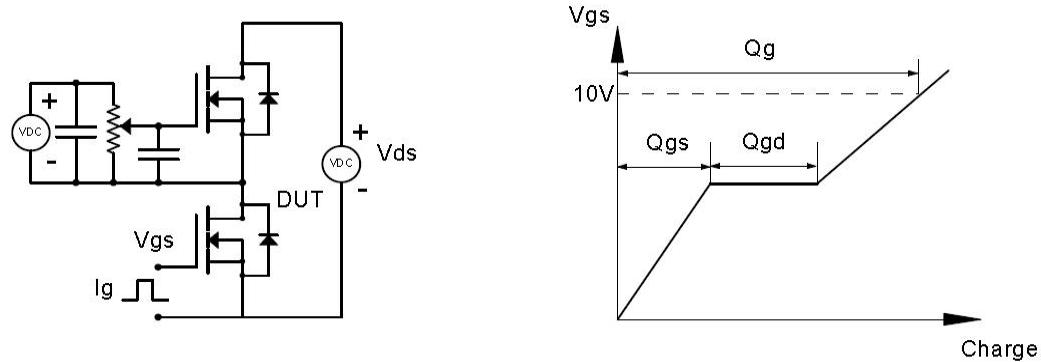


Figure 12. Transient Thermal Response Curve

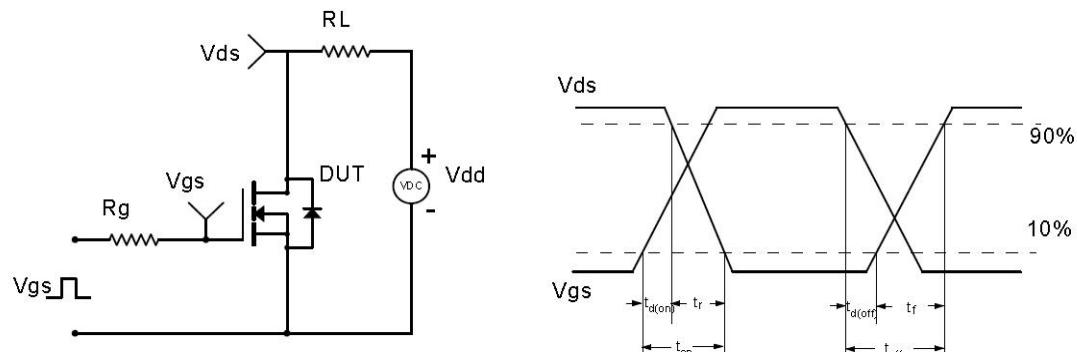


Test Circuit & Waveforms

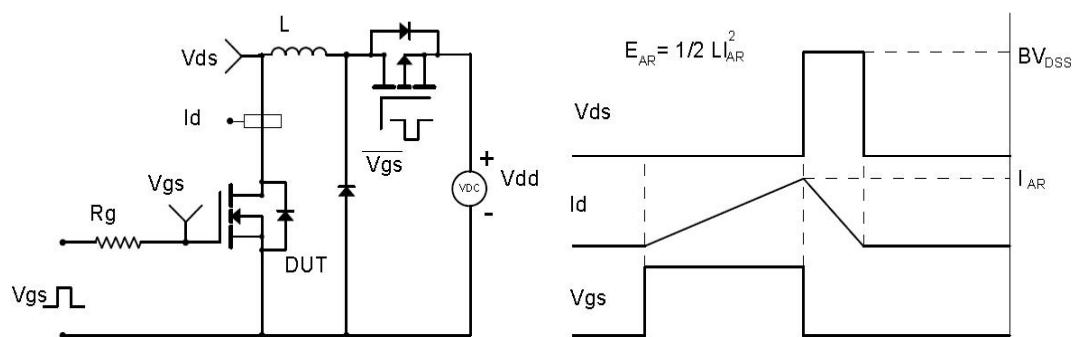
Gate Charge Test Circuit & Waveform



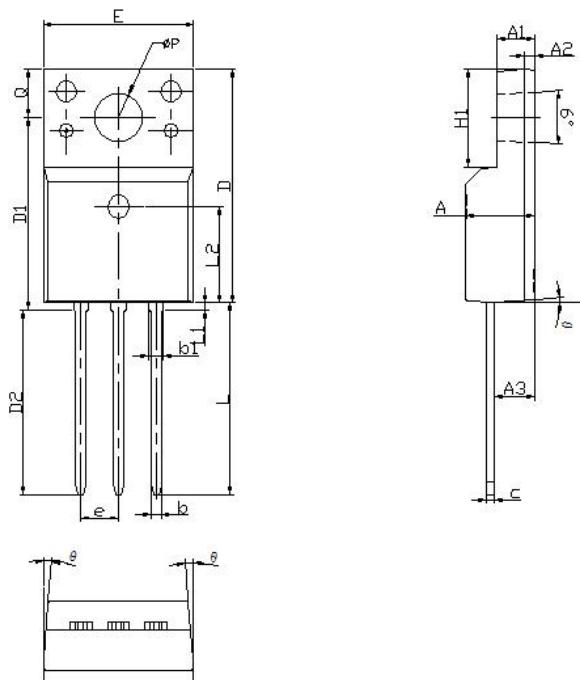
Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Mechanical Dimensions for TO-220NF



DIMENSIONS IN MILLIMETERS			DIMENSIONS IN INCHES	
SYMBOL	MIN	MAX	MIN	MAX
A	4.3	4.83	0.169	0.190
A1	2.34	2.9	0.092	0.114
A2	0.70REF		0.028REF	
A3	2.56	2.93	0.101	0.115
b	0.59	0.8	0.023	0.031
b1	—	1.1	—	0.043
c	0.45	0.79	0.018	0.031
D	14.7	16.07	0.579	0.633
D1	12.87	13.27	0.507	0.522
D2	12.28	12.68	0.483	0.499
E	9.7	10.36	0.382	0.408
e	2.54BSC		0.1BSC	
H1	6.48	7.1	0.255	0.280
L	12.68	13.35	0.499	0.526
L1	—	0.85	—	0.033
L2	6.50REF		0.256REF	
φP	3.05	3.4	0.120	0.134
Q	2.7	3.4	0.106	0.134
θ	1°	5°	1°	5°

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